

IDS U3-3861LE-C-HQ-VU-AF, USB 3.0, 1/2.8" Color Camera

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IDS Imaging uEye LE/XLE Camera (C/CS - Mount, Full Housing, Front View)



Stock **#78-152** NEW CONTACT US

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₹48,400

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SPECIFICATIONS

General

Color

Type:

IDS Imaging Development Systems	Manufacturer:
uEye+ LE-AF	Camera Family:
U3-3861LE-C-HQ-VU-AF	Model Number:
Physical & Mechanical Properties	
36 x 36 x 26 (excludes connectors and lens mount)	Dimensions (mm):
15	Weight (g):
Board Level	Housing:
Sensor	
Not Specified	Image Buffer:
Sony IMX290	Imaging Sensor:
Progressive Scan CMOS	Type of Sensor:
Rolling	Type of Shutter:
1/2.8"	Camera Sensor Format:
2.10	Resolution (MegaPixels):
1,936 x 1,096	Pixels (H x V):
2.90 x 2.90	Pixel Size, H x V (µm):
5.61 x 3.175	Sensing Area, H x V (mm):
135.00	Frame Rate (fps):
12 bit	Pixel Depth:
0.04ms - 1649ms	Exposure Time:
72.00	Dynamic Range (dB):
USB3 Vision	Machine Vision Standard:
Electrical	
1 - 1.5	Power Consumption (W):
Hardware & Interface Connectivity	
USB 3.0	Video Output:
USB Type-C	Connector:
Power over USB	Power Supply:
10-pin Wuerth connector (WR-WTB 1.00 mm)	GPIO Connector Type:
Threading & Mounting	
S-Mbunt	Mount:
Environmental & Durability Factors	
0 to +55	Operating Temperature (°C):
-20 to +80	Storage Temperature (°C):
Regulatory Compliance	
Compliant	RoHS:
View	Certificate of Conformance:

PRODUCT DETAILS

- Up to 8.0MP Resolution with Framerrates up to 230fps
- Board Level Options with C/CS-Mount or S-Mount Available
- GenICam USB3 Vision Compliant

IDS Imaging uEye LE/XLE USB3.1 Cameras utilize [IDS Imaging's peak SDK platform](#) that supports GenICam and USB3 Vision standards for ease of software development and integration. These cameras are available in board-level or housed options with S-Mount or C/CS-Mount versions. The C/CS-Mount configurations come with a 5mm spacer to easily adapt between C-Mount and CS-Mount lenses. IDS Imaging uEye LE/XLE USB3.1 Cameras are ideal for small device construction, medical technology, robotics, and machine vision applications. With a compact design, the XLE version is suitable for integration into embedded systems whereas the LE version is suitable for small device projects.
